

Certifications

Approved by ENEDIS

Section

MV Semi-conductor

Application

Field

Laboratory

**PRODUCT BENEFITS**

No silicon needed
 Fine tuning of the blade with a 'click' for each 1/10 mm
 Low roughness over insulation
 No Clamp stoper needed

TOOL CAPACITY

Diameter 12 - 44 mm
 0,472 - 1,732 inch

Thickness capacity 1,8 mm / 0,071 in

Angle of the chamfer on the semiconductor 13°

Remaining length of the semiconductor 25mm / 0,984 in

TOOL DIMENSIONS

Length 185 mm

Width 103 mm

Height 74 mm

Weight without box 0,525 Kg

Packaging Box

Tool to remove bonded semiconductor with chamfer on the semiconductor cutback

TO DO WHAT

The CWB/12-44 enables the user to remove the bonded semicon with a chamfer on the semiconductor cutback

**Options**

SGM - Large size pouch

Spare part

LCWB-FEP-V - Spare blade for bonded semiconductor with chamfer 13° + screw

Associated tool

GRI-RTE - Scraper for residues of bonded semiconductor screen with protective case

PG3HTA/2530 - Pliers for MV cables outer sheath

BRMRD1E - Tool to remove insulation

MV cables Tools

CWB/12-44



Part Number	Diameter	Tool capacity			Dimensions			Packaging
		Thickness capacity	Angle of the chamfer on the semiconductor	Remaining length of the semiconductor	Length	Width	Height	
CWB/12-44	12 - 44 mm 0,472 - 1,732 in	1,8 mm / 0,071 in	13°	25mm / 0,984 in	185 mm 7,283 in	103 mm 4,055 in	74 mm 2,913 in	box



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